TGn Sync, WWiSE and Mitmot closing report

Date: **2005-07-21**

Author				
Name	**Company**	**Address**	**Phone**	**Email**
Syed Aon Mujtaba	Agere Systems	555 Union Blvd., Allentown, PA 18109, USA	+1 610 712 6616	mujtaba@agere.com
Christopher Hansen	Broadcom	190 Mathilda Place, Sunnyvale, CA 94086	+1 408 543 3378	chansen@broadcom
Marc de Courville	Motorola	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69352518	Marc.de.Courville@motorola.com

Notice: This document has been prepared to assist IEEE 802.11. It is offered as a basis for discussion and is not binding on the contributing individual(s) or organization(s). The material in this document is subject to change in form and content after further study. The contributor(s) reserve(s) the right to add, amend or withdraw material contained herein.

Release: The contributor grants a free, irrevocable license to the IEEE to incorporate material contained in this contribution, and any modifications thereof, in the creation of an IEEE Standards publication; to copyright in the IEEE's name any IEEE Standards publication even though it may include portions of this contribution; and at the IEEE's sole discretion to permit others to reproduce in whole or in part the resulting IEEE Standards publication. The contributor also acknowledges and accepts that this contribution may be made public by IEEE 802.11.

Patent Policy and Procedures: The contributor is familiar with the IEEE 802 Patent Policy and Procedures <http:// ieee802.org/guides/bylaws/sb-bylaws.pdf>, including the statement "IEEE standards may include the known use of patent(s), including patent applications, provided the IEEE receives assurance from the patent holder or applicant with respect to patents essential for compliance with both mandatory and optional portions of the standard." Early disclosure to the Working Group of patent information that might be relevant to the standard is essential to reduce the possibility for delays in the development process and increase the likelihood that the draft publication will be approved for publication. Please notify the Chair <stuart.kerry@philips.com> as early as possible, in written or electronic form, if patented technology (or technology under patent application) might be incorporated into a draft standard being developed within the IEEE 802.11 Working Group. **If you have questions, contact the IEEE Patent Committee Administrator at <patcom@ieee.org>.**

INTEL-1029
10,079,707

Additional Authors:		
Name	**Company**	**email**
Adrian P. Stephens	Intel Corporation	Adrian.p.stephens@intel.com
Alek Purkovic	Nortel Networks	apurkovi@nortelnetworks.com
Alexander L. Cheng	C-cation, Inc	AlexCheng@C-cation.com
Andrew Myles	Cisco Systems	amyles@cisco.com
Andy Molisch	Mitsubishi Electric Corporation	molisch@merl.com
Brian Hart	Cisco Systems	brianh@cisco.com
Brian Johnson	Nortel Networks	brjohnso@nortelnetworks.com
Chiu Ngo	Samsung Electronics Co Ltd	chiu.ngo@samsung.com
Daisuke Takeda	Toshiba Corporation	daisuke.takeda@toshiba.co.jp
Daqing Gu	Mitsubishi Electric Corporation	dgu@merl.com
Darren McNamara	Toshiba Corporation	Darren.McNamara@toshiba-trel.com
David Bagby	Calypso Consulting	david.bagby@ieee.org
Dongjun (DJ) Lee	Samsung Electronic Co Ltd	djthekid.lee@samsung.com
Eldad Perahia	Cisco Systems	eperahia@cisco.com
Eldad Zeira	InterDigital Communications Corporation	eldad.zeira@interdigital.com
Fatih Ozluturk	InterDigital Communications Corporation	fatih.ozluturk@interdigital.com
Hiroshi Oguma	Tohoku University	oguma@wit.riec.tohoku.ac.jp
Hiroyuki Nakase	Tohoku University	nakase@riec.tohoku.ac.jp
Huanchun Ye	Atheros Communications	hcye@atheros.com
Hui-Ling Lou	Marvell Semiconductor	hlou@marvell.com
Isaac Lim Wei Lih	Panasonic	wllim@psl.com.sg
J. Mike Wilson	Intel Corporation	james.mike.wilson@intel.com
James Chen	Marvell Semiconductor	jamesc@marvell.com

Jin Zhang	Mitsubishi Electric Corporation	jzhang@merl.com
Job Oostveen	Royal Philips Electronics	job.oostveen@philips.com
Joe Pitarresi	Intel Corporation	joe.pitarresi@intel.com
John Ketchum	Qualcomm Incorporated	Johnk@qualcomm.com
Jon Rosdahl	Samsung Electronics Co Ltd	jon.rosdahl@partner.samsung.com
Jorg Habetha	Royal Philips Electronics	joerg.habetha@philips.com
Joseph Levy	InterDigital Communications Corporation	joseph.levy@interdigital.com
Kiyotaka Kobayashi	Panasonic	kobayashi.kiyotaka@jp.panasonic.com
Li Yuan	Institute for Infocomm Research	liyuan@i2r.a-star.edu.sg
Luke Qian	Cisco Systems	lchia@cisco.com
Mary Cramer	Agere Systems	mecramer@agere.com
Masahiro Takagi	Toshiba Corporation	masahiro3.takagi@toshiba.co.jp
Monisha Gosh	Royal Philips Electronics	monisha.ghosh@philips.com
Morgan Miki	Sharp	miki@slab.tnr.sharp.co.jp
Osama Aboul-Magd	Nortel Networks	osama@nortelnetworks.com
Paul Feinberg	Sony Electronics	paul.feinberg@am.sony.com
Pen Li	Royal Philips Electronics	pen.li@philips.com
Peter Loc	Marvell Semiconductor	ploc@marvell.com
Robert Stacey	Intel Corporation	Robert.j.stacey@intel.com
Ronald Rietman	Royal Phiips Electronics	ronald.rietman@philips.com
Sanjiv Nanda	Qualcomm Incorporated	snanda@qualcomm.com
Seigo Nakao	Sanyo Electric Co Ltd	snakao@gf.hm.rd.sanyo.co.jp
Sheung Li	Atheros Communications	sheung@atheros.com
Stephen Shellhammer	Qualcomm Incorporated	sshellham@qualcomm.com
Subra Dravida	Qualcomm Incorporated	subrad@qualcomm.com
Sudheer Grandhi	InterDigital Communications Corporation	sudheer.grandhi@interdigital.com

Sumei Sun	Institute for Infocomm Research	sunsm@i2r.a-star.edu.sg
Taekon Kim	Samsung Electronics Co Ltd	taekon.kim@samsung.com
Takashi Fukugawa	Panasonic	fukagawa.takashi@jp.panasonic.com
Takashi Shono	Intel Corporation	takashi.shono@intel.com
Takushi Kunihiro	Sony Corporation	kuni@wcs.sony.co.jp
Teik-Kheong (TK) Tan	Royal Philips Electronics	tktan@philips.com
Tomoko Adachi	Toshiba Corporation	tomo.adachi@toshiba.co.jp
Tomoya Yamaura	Sony Corporation	yamaura@wcs.sony.co.jp
Tsuguhide Aoki	Toshiba Corporation	tsuguhide.aoki@toshiba.co.jp
Won-Joon Choi	Atheros Communications	wjchoi@atheros.com
Xiaowen Wang	Agere Systems	xiaowenw@agere.com
Yasuhiko Tanabe	Toshiba Corporation	yasuhiko.tanabe@toshiba.co.jp
Yasuhiro Tanaka	Sanyo Electric Co Ltd	y_tanaka@gf.hm.rd.sanyo.co.jp
Yoshiharu Doi	Sanyo Electric Co Ltd	doi@gf.hm.rd.sanyo.co.jp
Youngsoo Kim	Samsung Electronic Co Ltd	KimYoungsoo@samsung.com
Yuichi Morioka	Sony Corporation	morioka@wcs.sony.co.jp
Yukimasa Nagai	Mitsubishi Electric Corporation	yuki-n@isl.melco.co.jp

Markus Muck	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69352573	muck@crm.mot.com
Jean-Noel Patillon	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69352522	patillon@crm.mot.com
Sebastien Simoens	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69352543	simoens@crm.mot.com
Stéphanie Rouquette	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69354824	stephanie.rouquette@motorola.com
Alexandre Ribeiro Dias	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 5 61191924	Alexandre.ribeirodias@motorola.com
Karine Gosse	Motorola Labs	Parc les Algorithmes, Gif-sur-Yvette 91193 France	+33 1 69352520	Karine.Gosse@motorola.com
Brian Classon	Motorola Labs	1301 E. Algonquin Rd, Schaumburg IL 60196 USA	+1 8475765675	Brian.Classon@motorola.com
Keith Blankenship	Motorola Labs	1301 E. Algonquin Rd, Schaumburg IL 60196 USA	+1 8475381311	Keith.Blankenship@motorola.com

VK Jones	Airgo Networks	vkjones@airgonetworks.com
Richard van Nee	Airgo Networks	richardvannnee@airgonetworks.com
Ali Raissinia	Airgo Networks	aliraissinia@airgonetworks.com
Allert van Zelst	Airgo Networks	allertvanzelst@airgonetworks.com
Bruce Edwards	Broadcom	bedwards@broadcom.com
Matthew Fischer	Broadcom	mfischer@broadcom.com
Chris Hansen	Broadcom	chansen@broadcom.com
Tushar Moorti	Broadcom	tushar@broadcom.com
Chris Young	Broadcom	cyoung@broadcom.com
Takashi Ishidoshiro	Buffalo	doshir@melcoinc.co.jp
Masato Kato	Buffalo	mkato@melcoinc.co.jp
Dave Hedberg	Conexant	dave.hedberg@conexant.com
Cenk Kose	Conexant	cenk.kose@conexant.com
Jim Petranovich	Conexant	jim.petranovich@conexant.com

Michael Seals	Conexant	michael.seals@conexant.com
Mark Webster	Conexant	mark.webster@conexant.com
Menzo Wentink	Conexant	menzo.wentink@conexant.com
Taehyun Jeon	ETRI	thjeon@etri.re.kr
Sok-kyu Lee	ETRI	sk-lee@etri.re.kr
Heejung Yu	ETRI	heejung@etri.re.kr
Mustafa Eroz	Hughes Network Systems	feroz@hns.com
Lakshmi Iyer	Hughes Network Systems	liyer@hns.com
Lin-Nan Lee	Hughes Network Systems	llee@hns.com
Feng-Wen Sun	Hughes Network Systems	fsun@hns.com
Marc de Courville	Motorola	marc.de.courville@motorola.com
Markus Muck	Motorola	markus.muck@motorola.com
Alexandre Ribeiro-Dias	Motorola	alexandre.ribeirodias@motorola.com

Stephanie Rouquette-Leveil	Motorola	stephanie.rouquette@motorola.com
Sebastien Simoens	Motorola	sebastien.simoens@motorola.com
Nico van Waes	Nokia	Nico.vanWaes@nokia.com
John Chang	Ralink	john_chang@ralinktech.com.tw
Sheng Lee	Ralink	shenghlee@ralinktech.com
Tom Pare	Ralink	tpare@ralinktech.com
David Tung	Ralink	dtung@ralinktech.com
Der-Zheng Liu	Realtek	dzliu@realtek.com.tw
Ravi Mahadevappa	Realtek	ravi@realtek-us.com
Stephan ten Brink	Realtek	stenbrink@realtek-us.com
Gabriella Convertino	STMicroelectronics	gabriella.convertino@st.com
Mike Moreton	STMicroelectronics	mike.moreton@st.com
Fabio Osnato	STMicroelectronics	fabio.osnato@st.com
Pratima Pai	STMicroelectronics	pratima.pai@st.com

Vincenzo Scarpa	STMicroelectronics	vincenzo.scarpa@st.com
Massimiliano Siti	STMicroelectronics	massimiliano.siti@st.com
George Vlantis	STMicroelectronics	george.vlantis@st.com
Anuj Batra	Texas Instruments	batra@ti.com
Srikanth Gummadi	Texas Instruments	sgummadi@ti.com
Dale Hocevar	Texas Instruments	hocevar@ti.com
Richard Williams	Texas Instruments	richard@ti.com
Keith Chugg	TrellisWare	kchugg@trellisware.com
Paul Gray	TrellisWare	pgray@trellisware.com
Bob Ward	TrellisWare	bward@trellisware.com
Jeng-Hong Chen	Winbond Electronics	jhchen2@winbond.com
Pansop Kim	Winbond Electronics	pkim@winbond.com
Alfred Lin	Winbond Electronics	halin@winbond.com
Wei-Chung Peng	Winbond Electronics	wcpeng0@winbond.com

Abstract

- This document provides an update on the joint proposal effort this week among TGn Sync, WWiSE, and Mitmot

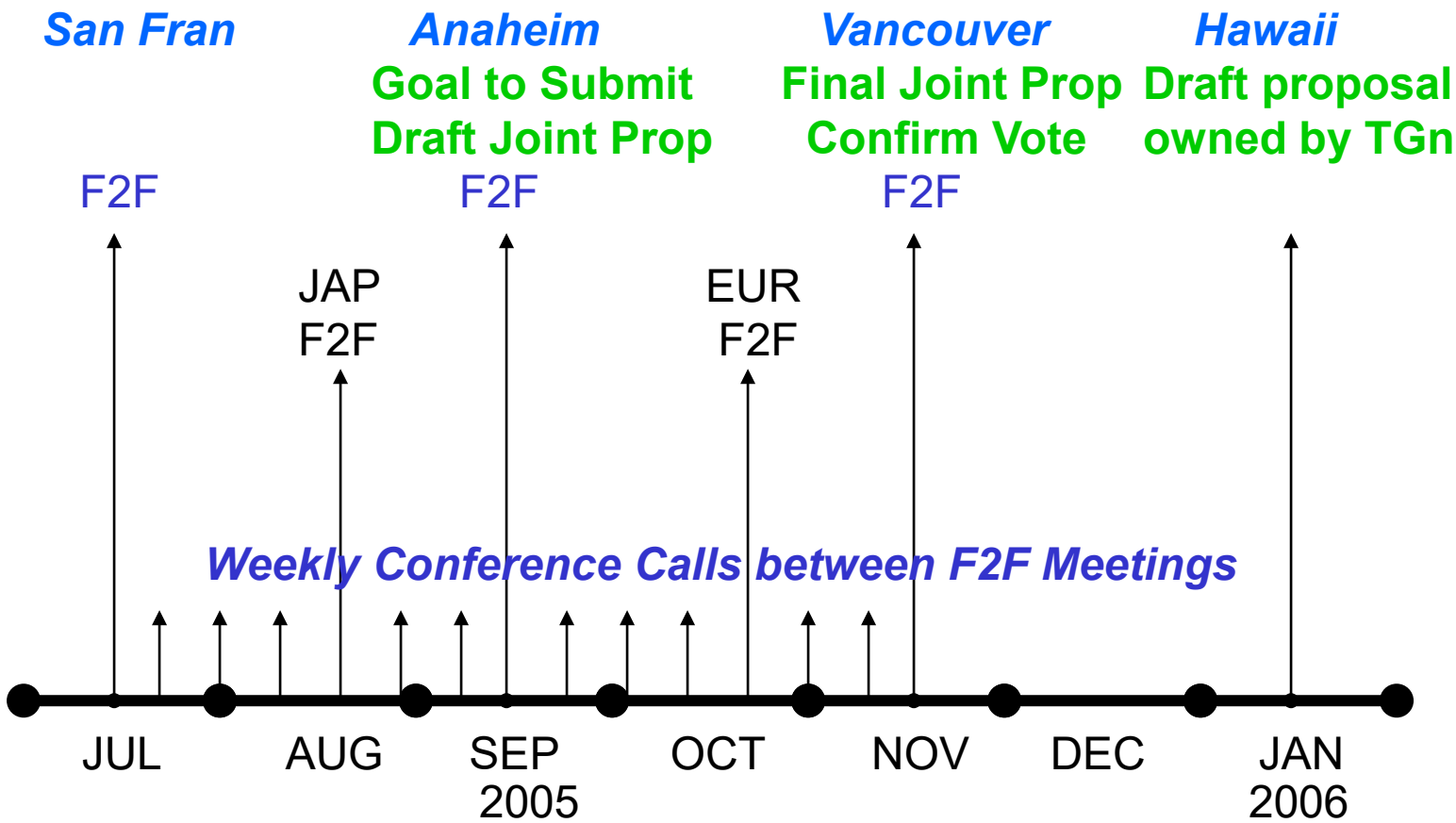
Procedural Updates

- Adopted a process for creating the joint proposal
  - Adopted a decision making procedure
  - Agreed on web tools to help facilitate document sharing and conference calls
- Established a firm and aggressive schedule for F2F and conference calls

PHY/MAC Teams Update

- Created a sequence of discussion points
- Discussed motions for adding draft text to the joint proposal
- Fielded detailed technical presentations on topics of mutual interest
- Created tiger teams to accelerate technical progress

Next Steps

- Weekly conference calls, starting next week
  - One for the MAC, one for the PHY
- F2F meeting in Japan in August
- Will upload one week prior to IEEE in Anaheim either a draft joint proposal or a progress report

Joint Proposal Timeline